

# TQP3M9035

## High Linearity LNA Gain Block

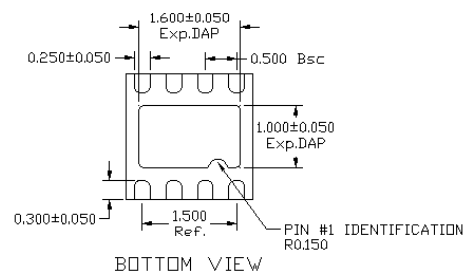
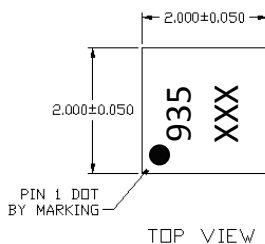


### Mechanical Information

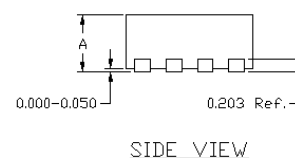
#### Package Information and Dimensions

This package is lead-free/RoHS-compliant. The plating material on the backside and leads is annealed matte tin.

The component will be marked with a “935” designator with an alphanumeric lot code on the top surface of package. The “XXX” is an auto generated number.

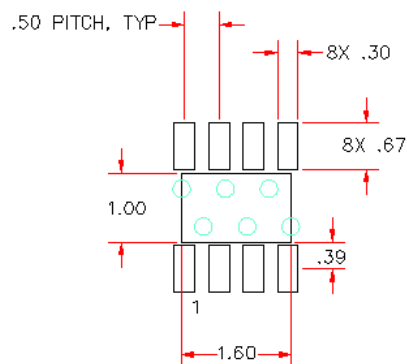
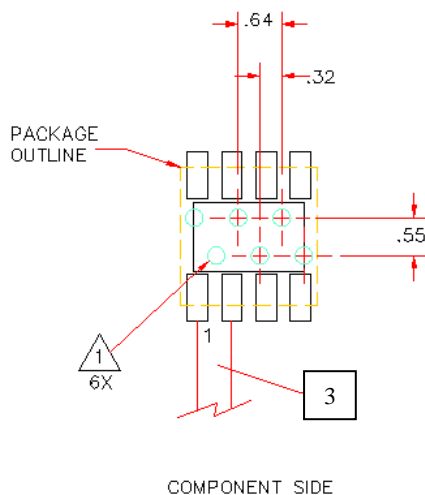


A	MAX.	SLP
	0.900	
	NDM.	0.850
	MIN.	0.800



#### PCB Mounting Pattern

All dimensions are in millimeters (inches). Angles are in degrees.



#### Notes:

1. Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
2. Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
3. RF trace width depends upon the PC board material and construction.
4. Use 1 oz. Copper minimum.